

## Automotive-grade N-Channel 40 V, 5.5 mΩ typ., 80 A STripFET™ F6 Power MOSFET in a D<sup>2</sup>PAK package

Datasheet - production data

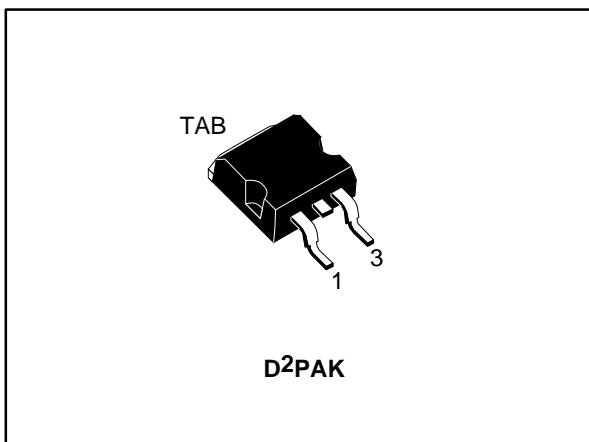
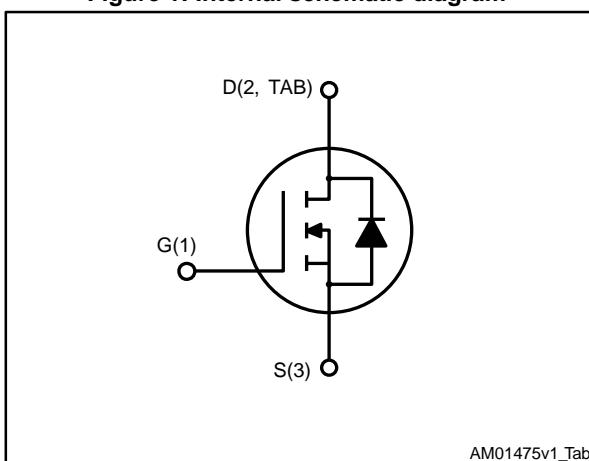


Figure 1: Internal schematic diagram



### Features

Order code	V <sub>DS</sub>	R <sub>DS(on)</sub> max.	I <sub>D</sub>
STB80N4F6AG	40 V	6 mΩ	80 A

- Designed for automotive applications and AEC-Q101 qualified
- Very low on-resistance
- Very low gate charge
- High avalanche ruggedness
- Low gate drive power loss

### Applications

- Switching applications

### Description

This device is an N-channel Power MOSFET developed using the STripFET™ F6 technology with a new trench gate structure. The resulting Power MOSFET exhibits very low R<sub>DS(on)</sub> in all packages.

Table 1: Device summary

Order code	Marking	Package	Packaging
STB80N4F6AG	80N4F6	D <sup>2</sup> PAK	Tape and Reel

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# 1 Electrical ratings

Table 2: Absolute maximum ratings

Symbol	Parameter	Value	Unit
$V_{DS}$	Drain-source voltage	40	V
$V_{GS}$	Gate-source voltage	$\pm 20$	V
$I_D$	Drain current (continuous) at $T_C = 25^\circ\text{C}$	80	A
$I_D$	Drain current (continuous) at $T_C = 100^\circ\text{C}$	56	A
$I_{DM}^{(1)}$	Drain current (pulsed)	320	A
$P_{TOT}$	Total dissipation at $T_C = 25^\circ\text{C}$	70	W
$I_{AV}$	Avalanche current, repetitive or not-repetitive (pulse width limited by $T_J$ max)	40	A
$E_{AS}$	Single pulse avalanche energy(Starting $T_J = 25^\circ\text{C}$ , $= I_D = I_{AV}$ , $V_{DD} = 25\text{ V}$ )	149	mJ
$T_{stg}$	Storage temperature	- 55 to 175	$^\circ\text{C}$
$T_j$	Max. operating junction temperature	175	$^\circ\text{C}$

**Notes:**

(1) Pulse width limited by safe operating area.

Table 3: Thermal data

Symbol	Parameter	Value	Unit
$R_{thj-case}$	Thermal resistance junction-case max.	2.14	$^\circ\text{C}/\text{W}$
$R_{thj-pcb}^{(1)}$	Thermal resistance junction-ambient max.	35	$^\circ\text{C}/\text{W}$

**Notes:**(1) When mounted on FR-4 board of inch<sup>2</sup>, 2 oz Cu

## 2 Electrical characteristics

( $T_C = 25^\circ\text{C}$  unless otherwise specified).

**Table 4: On/Off States**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(\text{BR})\text{DSS}}$	Drain-source breakdown voltage	$V_{GS} = 0 \text{ V}$ , $I_D = 250 \mu\text{A}$	40			V
$I_{\text{DSS}}$	Zero gate voltage drain current ( $V_{GS} = 0 \text{ V}$ )	$V_{DS} = 40 \text{ V}$			1	$\mu\text{A}$
		$V_{DS} = 40 \text{ V}$ $T_J = 125^\circ\text{C}$			100	$\mu\text{A}$
$I_{GSS}$	Gate-body leakage current ( $V_{DS} = 0 \text{ V}$ )	$V_{GS} = \pm 20 \text{ V}$			$\pm 100$	nA
$V_{GS(\text{th})}$	Gate threshold voltage	$V_{DS} = V_{GS}$ , $I_D = 250 \mu\text{A}$	2		4	V
$R_{DS(\text{on})}$	Static drain-source on-resistance	$V_{GS} = 10 \text{ V}$ , $I_D = 40 \text{ A}$		5.5	6	$\text{m}\Omega$

**Table 5: Dynamic**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$C_{iss}$	Input capacitance	$V_{DS} = 25 \text{ V}$ , $f = 1 \text{ MHz}$ , $V_{GS} = 0 \text{ V}$	-	2150	-	pF
$C_{oss}$	Output capacitance		-	335	-	pF
$C_{rss}$	Reverse transfer capacitance		-	160	-	pF
$Q_g$	Total gate charge	$V_{DD} = 20 \text{ V}$ , $I_D = 80 \text{ A}$ , $V_{GS} = 10 \text{ V}$ (see <a href="#">Figure 14: "Test circuit for gate charge behavior"</a> )	-	36	-	nC
$Q_{gs}$	Gate-source charge		-	11	-	nC
$Q_{gd}$	Gate-drain charge		-	9	-	nC

**Table 6: Switching times**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$	Turn-on delay time	$V_{DD} = 20 \text{ V}$ , $I_D = 40 \text{ A}$ , $R_G = 4.7 \Omega$ , $V_{GS} = 10 \text{ V}$ (see <a href="#">Figure 15: "Test circuit for inductive load switching and diode recovery times"</a> )	-	10.5	-	ns
$t_r$	Rise time		-	7.6	-	ns
$t_{d(off)}$	Turn-off-delay time		-	46.1	-	ns
$t_f$	Fall time		-	11.9	-	ns

Table 7: Source-drain diode

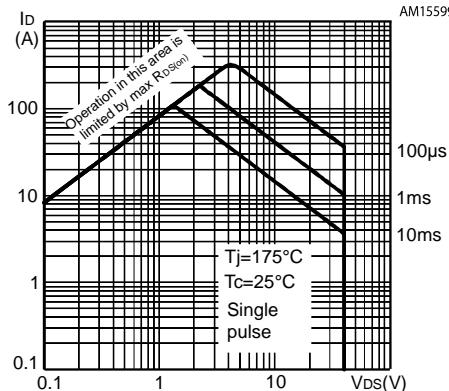
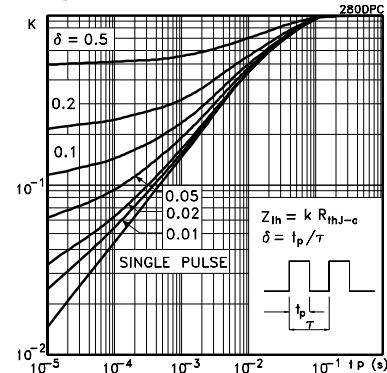
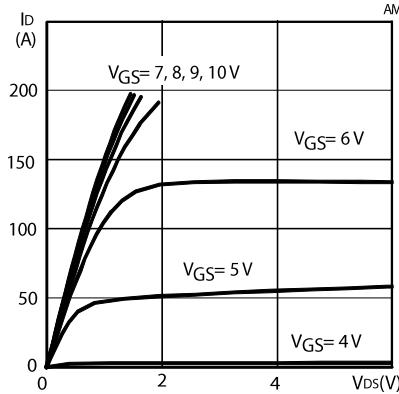
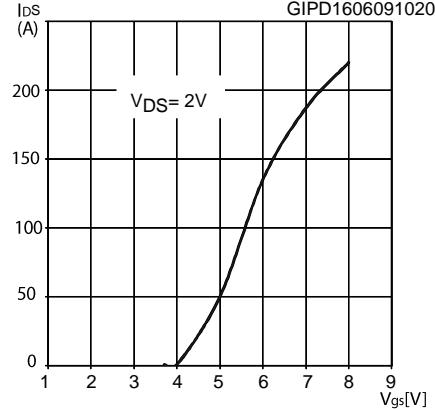
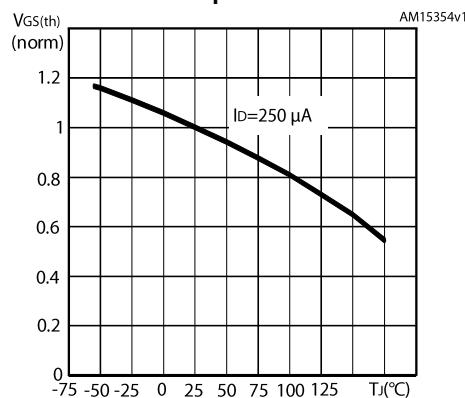
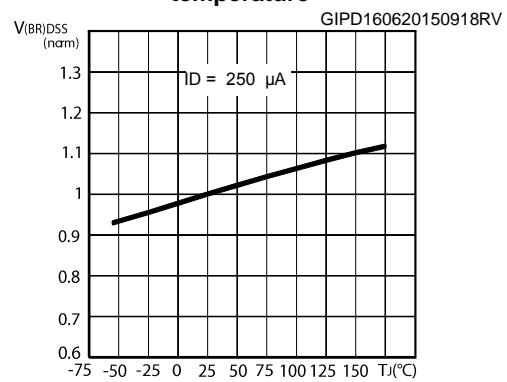
Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$I_{SD}$	Source drain current				80	A
$I_{SDM}^{(1)}$	Source-drain current (pulsed)				320	A
$V_{SD}^{(2)}$	Forward on voltage	$I_{SD} = 40 \text{ A}, V_{GS} = 0 \text{ V}$			1.3	V
$t_{rr}$	Reverse recovery time	$I_{SD} = 80 \text{ A}, dI/dt = 100 \text{ A}/\mu\text{s}, V_{DD} = 32 \text{ V}$ (See <i>Figure 17: "Unclamped inductive waveform"</i> )		41.1		ns
$Q_{RR}$	Reverse recovery charge			43.6		nC
$I_{RRM}$	Reverse recovery current			2.1		A

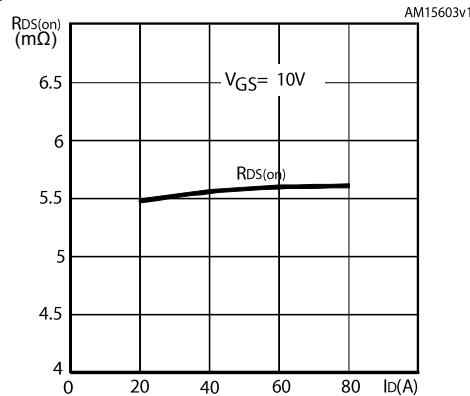
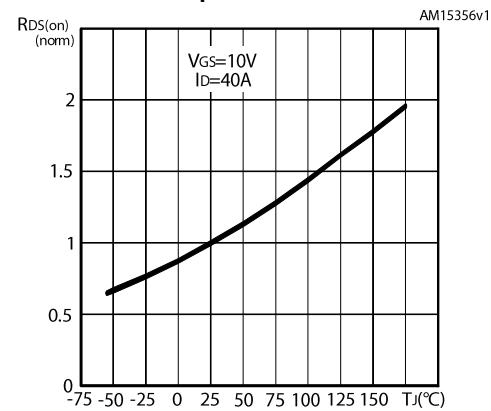
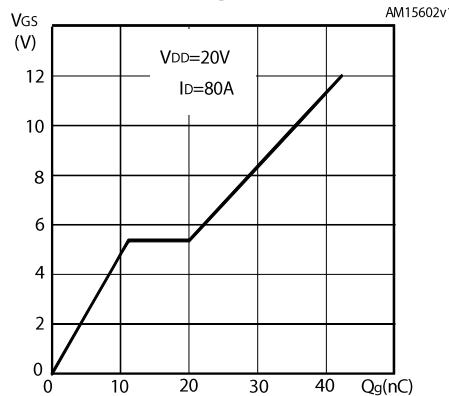
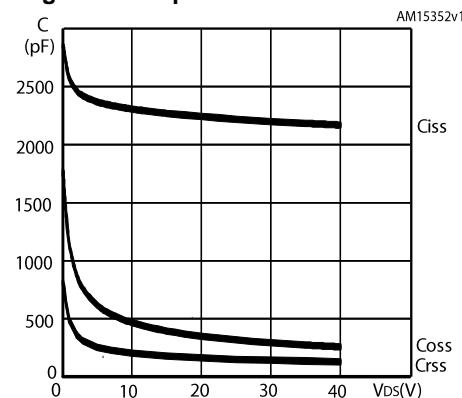
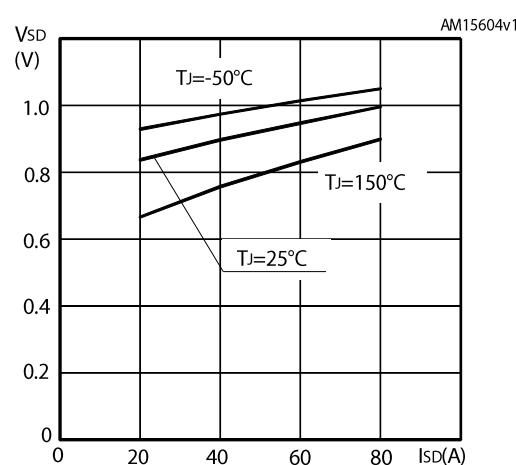
**Notes:**

(1)Pulse width limited by safe operating area.

(2)Pulsed: pulse duration = 300  $\mu\text{s}$ , duty cycle 1.5%

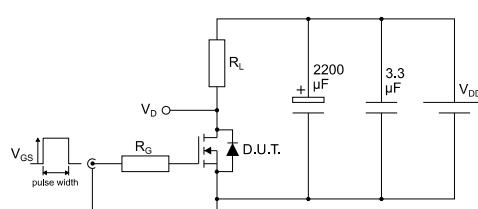
## 2.1 Electrical characteristics (curves)

**Figure 2: Safe operating area****Figure 3: Thermal impedance****Figure 4: Output characteristics****Figure 5: Transfer characteristics****Figure 6: Normalized gate threshold voltage vs. temperature****Figure 7: Normalized V(BR)DSS vs. temperature**

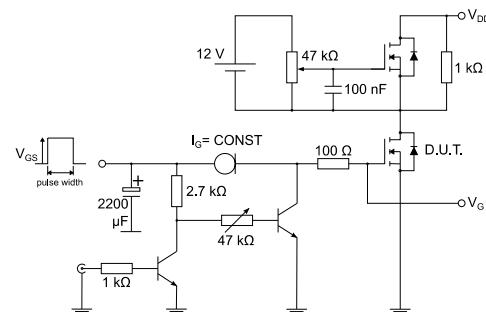
**Figure 8: Static drain-source on-resistance****Figure 9: Normalized on-resistance vs. temperature****Figure 10: Gate charge vs. gate-source voltage****Figure 11: Capacitance variations****Figure 12: Source- drain diode forward characteristics**

### 3 Test circuits

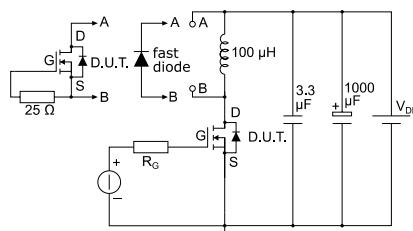
**Figure 13: Test circuit for resistive load switching times**



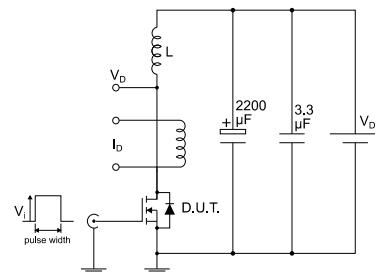
**Figure 14: Test circuit for gate charge behavior**



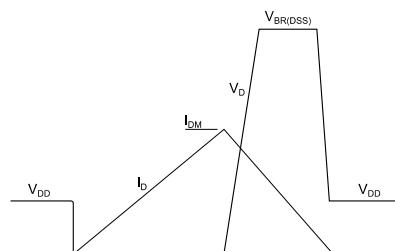
**Figure 15: Test circuit for inductive load switching and diode recovery times**



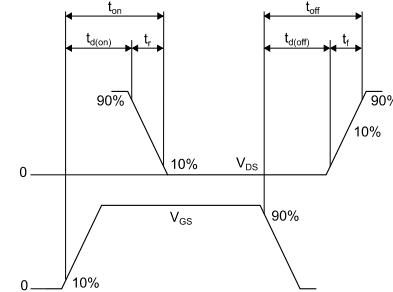
**Figure 16: Unclamped inductive load test circuit**



**Figure 17: Unclamped inductive waveform**



**Figure 18: Switching time waveform**



## 4 Package mechanical data

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: [www.st.com](http://www.st.com).  
ECOPACK® is an ST trademark.

### 4.1 D<sup>2</sup>PAK package information

Figure 19: D<sup>2</sup>PAK (TO-263) type A package outline

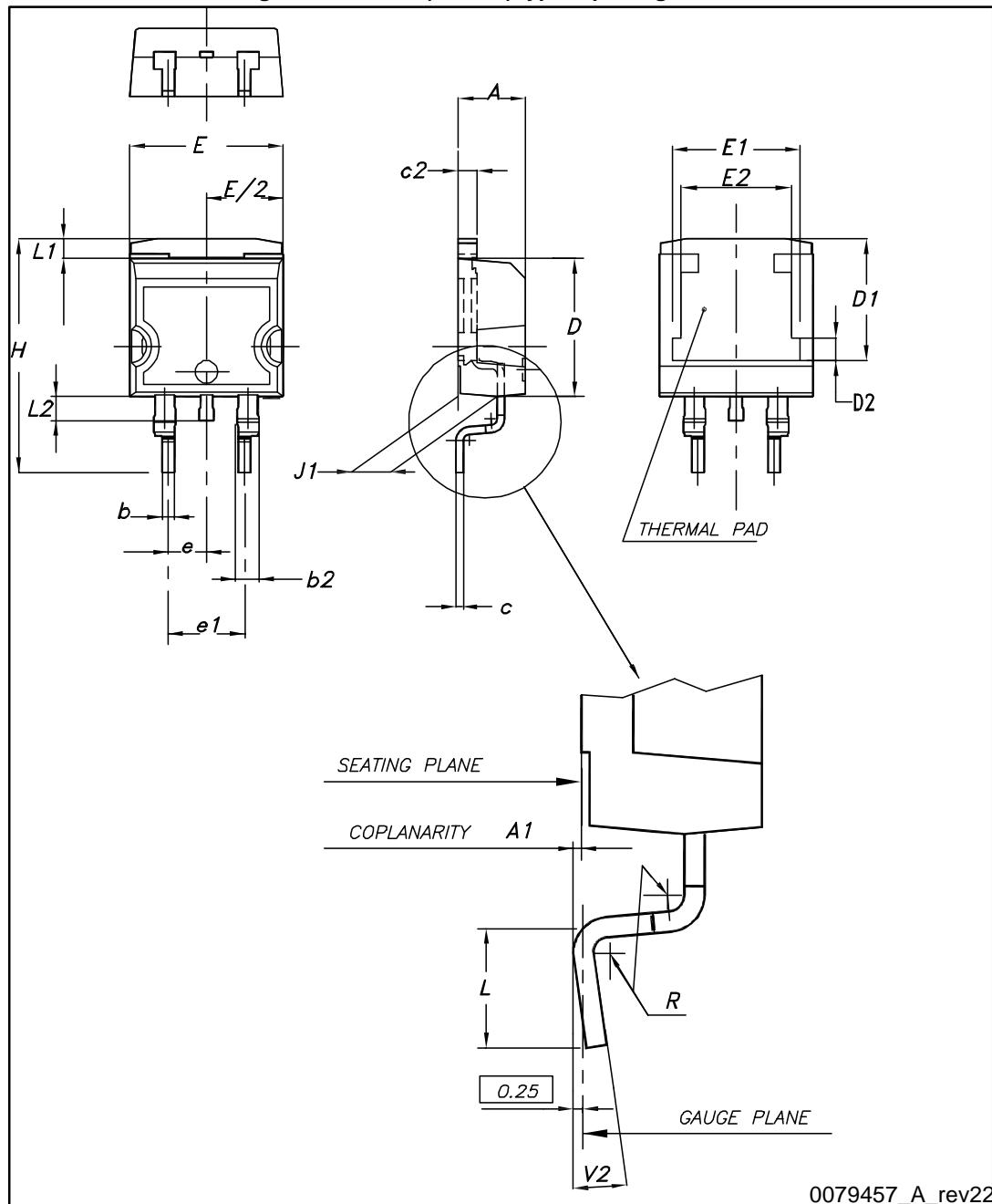
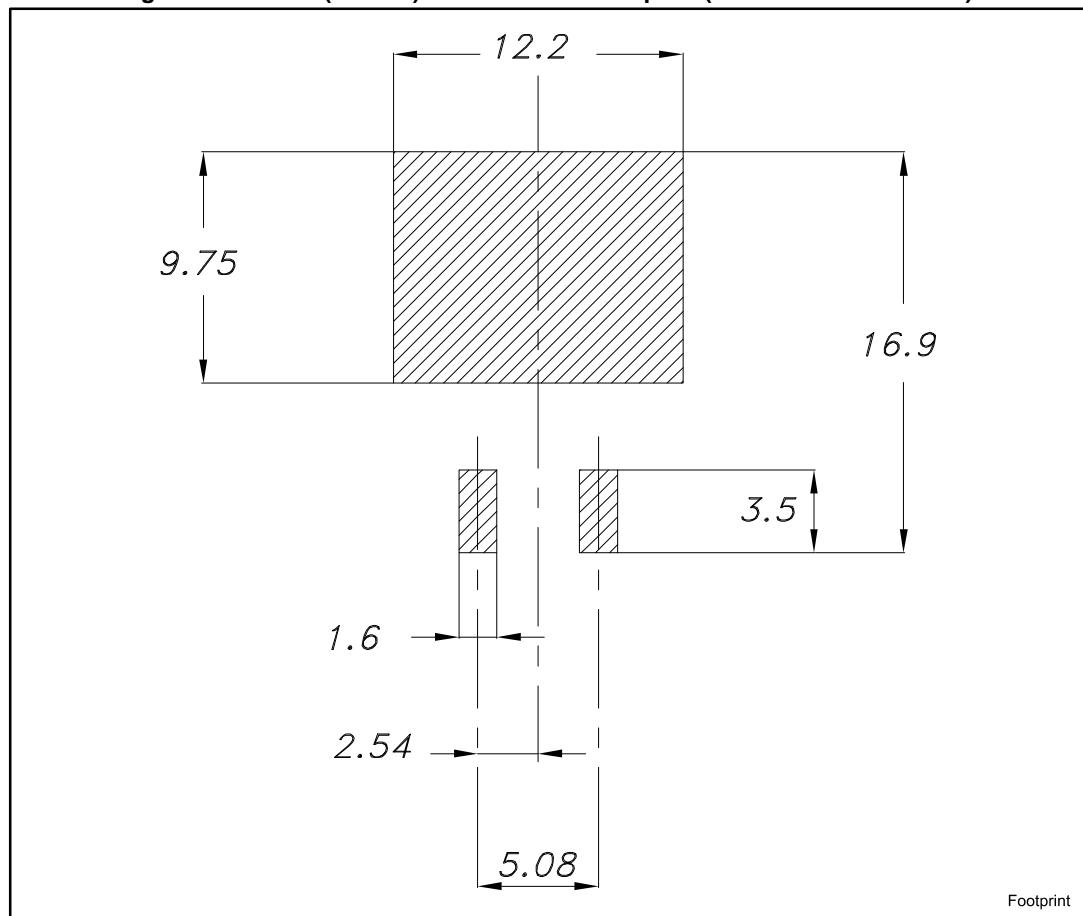


Table 8: D<sup>2</sup>PAK (TO-263) type A package mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	4.40		4.60
A1	0.03		0.23
b	0.70		0.93
b2	1.14		1.70
c	0.45		0.60
c2	1.23		1.36
D	8.95		9.35
D1	7.50	7.75	8.00
D2	1.10	1.30	1.50
E	10		10.40
E1	8.50	8.70	8.90
E2	6.85	7.05	7.25
e		2.54	
e1	4.88		5.28
H	15		15.85
J1	2.49		2.69
L	2.29		2.79
L1	1.27		1.40
L2	1.30		1.75
R		0.4	
V2	0°		8°

Figure 20: D<sup>2</sup>PAK (TO-263) recommended footprint (dimensions are in mm)

## 4.2 D<sup>2</sup>PAK packing information

Figure 21: Tape outline

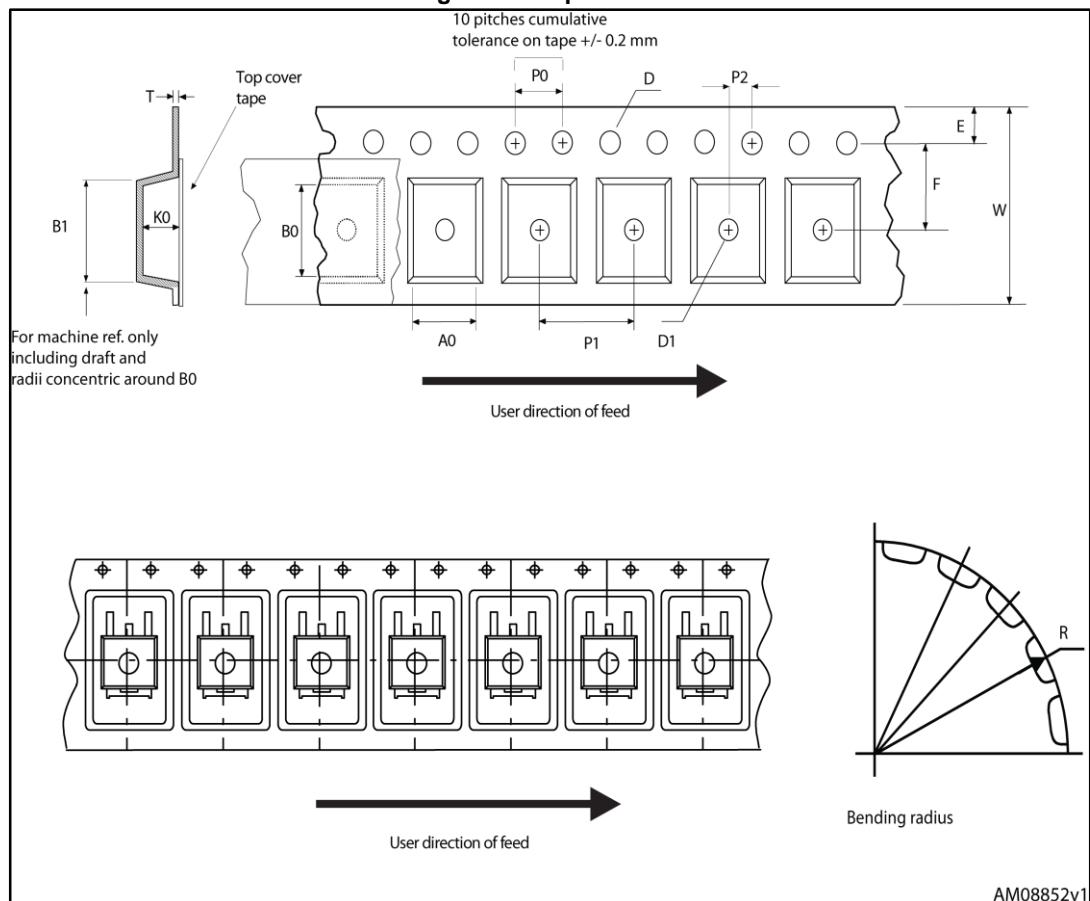
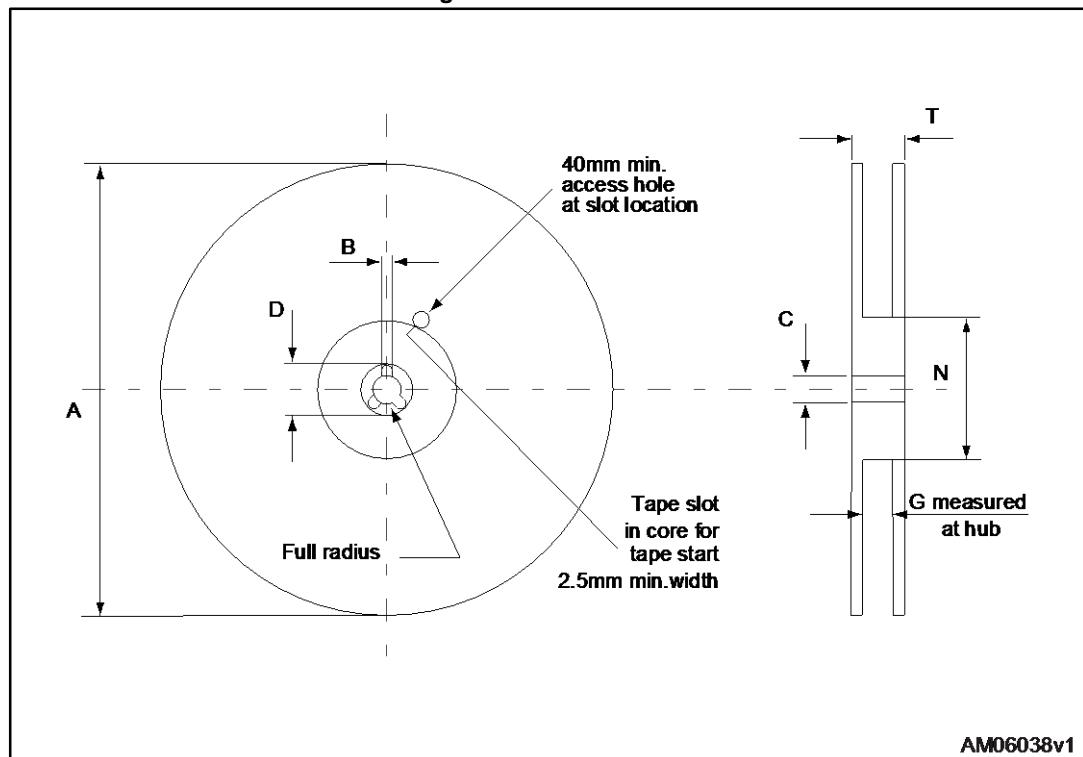


Figure 22: Reel outline

Table 9: D<sup>2</sup>PAK tape and reel mechanical data

Tape			Reel		
Dim.	mm		Dim.	mm	
	Min.	Max.		Min.	Max.
A0	10.5	10.7	A		330
B0	15.7	15.9	B	1.5	
D	1.5	1.6	C	12.8	13.2
D1	1.59	1.61	D	20.2	
E	1.65	1.85	G	24.4	26.4
F	11.4	11.6	N	100	
K0	4.8	5.0	T		30.4
P0	3.9	4.1			
P1	11.9	12.1	Base quantity		1000
P2	1.9	2.1	Bulk quantity		1000
R	50				
T	0.25	0.35			
W	23.7	24.3			

## 5 Revision history

Table 10: Document revision history

Date	Revision	Changes
16-Jun-2015	1	Initial release
18-Nov-2015	2	Document status promoted from preliminary to production data. Updated title and features in cover page.

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